











TLC2272, TLC2272A, TLC2272M, TLC2272AM TLC2274, TLC2274A, TLC2274M, TLC2274AM

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TLC227x, TLC227xA: Advanced LinCMOS Rail-to-Rail Operational Amplifiers

Features

- Output Swing Includes Both Supply Rails
- Low Noise: 9 nV/ $\sqrt{\text{Hz}}$ Typical at f = 1 kHz
- Low-Input Bias Current: 1-pA Typical
- Fully-Specified for Both Single-Supply and Split-Supply Operation
- Common-Mode Input Voltage Range Includes Negative Rail
- High-Gain Bandwidth: 2.2-MHz Typical
- High Slew Rate: 3.6-V/µs Typical
- Low Input Offset Voltage: 950 µV Maximum at $T_A = 25^{\circ}C$
- Macromodel Included
- Performance Upgrades for the TLC272 and TLC274
- Available in Q-Temp Automotive

Applications

- White Goods (Refrigerators, Washing Machines)
- Hand-held Monitoring Systems
- Configuration Control and Print Support
- Transducer Interfaces
- **Battery-Powered Applications**

3 Description

The TLC2272 and TLC2274 are dual and quadruple operational amplifiers from Texas Instruments. Both devices exhibit rail-to-rail output performance for increased dynamic range in single- or split-supply applications. The TLC227x family offers 2 MHz of bandwidth and 3 V/µs of slew rate for higher-speed applications. These devices offer comparable AC performance while having better noise, input offset voltage, and power dissipation than existing CMOS operational amplifiers. The TLC227x has a noise voltage of 9 nV/\(\sqrt{Hz}\), two times lower than competitive solutions.

The TLC227x family of devices, exhibiting high input impedance and low noise, is excellent for small-signal conditioning for high-impedance sources such as piezoelectric transducers. Because of the micropower dissipation levels, these devices work well in handheld monitoring and remote-sensing applications. In addition, the rail-to-rail output feature, with single- or split-supplies, makes this family a great choice when interfacing with analog-to-digital converters (ADCs). For precision applications, the TLC227xA family is available with a maximum input offset voltage of 950 µV. This family is fully characterized at 5 V and ±5 V.

The TLC227x also make great upgrades to the TLC27x in standard designs. They offer increased output dynamic range, lower noise voltage, and lower input offset voltage. This enhanced feature set allows them to be used in a wider range of applications. For applications that require higher output drive and wider input voltage range, see the TLV2432 and TLV2442 devices.

If the design requires single amplifiers, see the TLV2211, TLV2221 and TLV2231 family. These devices are single rail-to-rail operational amplifiers in the SOT-23 package. Their small size and low power consumption make them ideal for high density, battery-powered equipment.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
	TSSOP (8)	4.40 mm × 3.00 mm
TLC2272	SOIC (8)	3.91 mm × 4.90 mm
1L02212	SO (8)	5.30 mm × 6.20 mm
	PDIP (8)	6.35 mm × 9.81 mm
	TSSOP (14)	4.40 mm × 5.00 mm
	SOIC (14)	3.91 mm × 8.65 mm
TLC2274	SO (14)	5.30 mm × 10.30 mm
	PDIP (14)	6.35 mm × 19.30 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Maximum Peak-to-Peak Output Voltage vs **Supply Voltage**

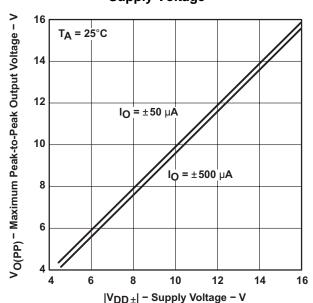




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4 Revision History

Changes from Revision G (May 2004) to Revision H

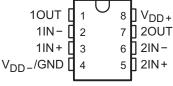
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Added Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Supportsection, and Mechanical, Packaging, and Orderable Information section.
 Added ESD Rating table for the D and PW package devices.

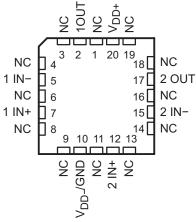


5 Pin Configuration and Functions

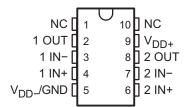
TLC2272
D, JG, P, or PW Package
8-Pin SOIC, CDIP, PDIP, or TSSOP
Top View



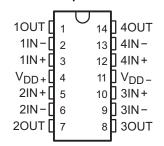




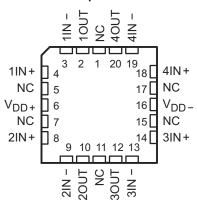
TLC2272 U Package 10-Pin CFP Top View



TLC2274 D, J, N, PW, or W Package 14-Pin SOIC, CDIP, PDIP, TSSOP, or CFP Top View



TLC2274 FK Package 20-Pin LCCC Top View





Pin Functions

		PII	N				
			NO.				
NAME	TLC2272			TLC	2274	1/0	DESCRIPTION
102	D, JG, P, or PW	FK	U	D, J, N, PW, or W	FK		
1IN+	3	7	4	3	4	I	Non-inverting input, Channel 1
1IN-	2	5	3	2	3	I	Inverting input, Channel 1
10UT	1	2	2	1	2	0	Output, Channel 1
2IN+	5	12	6	5	8	I	Non-inverting input, Channel 2
2IN-	6	15	7	6	9	I	Inverting input, Channel 2
2OUT	7	17	8	7	10	0	Output, Channel 2
3IN+	_	_	_	10	14	I	Non-inverting input, Channel 3
3IN-	_	_	_	9	13	I	Inverting input, Channel 3
3OUT	_	_	_	8	12	0	Output, Channel 3
4IN+	_	_	_	12	18	I	Non-inverting input, Channel 4
4IN-	_	_	_	13	19	1	Inverting input, Channel 4
4OUT	_	_	_	14	20	0	Output, Channel 4
V_{DD+}	8	20	9	4	6	_	Positive (highest) supply
V_{DD-}	_	_	_	11	16	_	Negative (lowest) supply
V _{DD} _/GND	4	10	5	_	_	_	Negative (lowest) supply
NC	_	1, 3, 4, 6, 8, 9, 11, 13, 14, 16, 18, 19	1, 10	_	1, 5, 7, 11, 15, 17	_	No Connection



Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
Supply voltage, V _{DD} + ⁽²⁾			8	V
V _{DD} - ⁽²⁾		-8		V
Differential input voltage, V _{ID} ⁽³⁾			±16	V
Input voltage, V _I (any input) ⁽²⁾		V _{DD} 0.3	V_{DD+}	V
Input current, I _I (any input)			±5	mA
Output current, I _O		±50	mA	
Total current into V _{DD+}			±50	mA
Total current out of V _{DD}			±50	mA
Duration of short-circuit current at (or below) 25°C (4)		Unlim		
	C level parts	0	70	
Operating free-air temperature range, T _A	I, Q level parts	-40	125	°C
	M level parts	-55	125	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	D, N, P or PW package		260	°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	J or U package		300	°C
Storage temperature, T _{stg}	Storage temperature, T _{stg}		150	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, except differential voltages, are with respect to the midpoint between V_{DD+} and V_{DD}.
 (3) Differential voltages are at IN+ with respect to IN-. Excessive current will flow if input is brought below V_{DD-} - 0.3 V.

6.2 ESD Ratings

				VALUE	UNIT
V _(ESD)	Flootrootatic discharge	Human-body model (HBM), per AEC Q100-002 ⁽¹⁾	Q-grade and M-grade devices in D and PW packages	±2000	V
	Electrostatic discharge	Charged-device model (CDM), per AEC Q100-011	Q-grade and M-grade devices in D and PW packages	±1000	\ \ \

⁽¹⁾ AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

			MIN	MAX	UNIT
		C LEVEL PARTS	±2.2	±8	
V _{DD±} S	Supply valtage	I LEVEL PARTS	±2.2	±8	V
	Supply voltage	Q LEVEL PARTS	±2.2	±8	V
		M LEVEL PARTS	±2.2	±8	
.,		C LEVEL PARTS	V _{DD} -	V _{DD+} −1.5	
	In put volto so	I LEVEL PARTS	V_{DD-}	V _{DD+} −1.5	V
VI	Input voltage	Q LEVEL PARTS	V _{DD} -	V _{DD+} −1.5	V
		M LEVEL PARTS	V_{DD-}	V _{DD+} −1.5	
		C LEVEL PARTS	V _{DD} -	V _{DD+} −1.5	
	0	I LEVEL PARTS	V_{DD-}	V _{DD+} −1.5	
V _{IC}	Common-mode input voltage	Q LEVEL PARTS	V _{DD} -	V _{DD+} −1.5	V
		M LEVEL PARTS	V _{DD} -	V _{DD+} −1.5	

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The output may be shorted to either supply. Temperature or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.



Recommended Operating Conditions (continued)

		MIN	MAX	UNIT	
T _A		C LEVEL PARTS	0	70	
		I LEVEL PARTS	-40	125	°C
	Operating free-air temperature	Q LEVEL PARTS	-40	125	• 0
		M LEVEL PARTS	-55	125	

6.4 Thermal Information

				TLC2272			TLC2274					
THERMAL METRIC ⁽¹⁾		D (SOIC)	P (PDIP)	PW (TSSOP)	FK (LCCC)	U (CFP)	D (SOIC)	N (PDIP)	PW (TSSOP)	FK (LCCC)	J (CDIP)	UNIT
		8-PIN	8-PIN	8-PIN	20-PIN	10-PIN	14-PIN	14-PIN	14-PIN	20-PIN	14-PIN	
$R_{\theta JA}$	Junction-to-ambient thermal resistance (2)(3)	115.6	58.5	175.8	_	_	83.8	_	111.6	_	_	°C/W
R _{0JC(top)}	Junction-to-case (top) thermal resistance (2)(3)	61.8	48.3	58.8	18	121.3	43.2	34	41.2	16	16.2	°C/W
R _{θJB}	Junction-to-board thermal resistance	55.9	35.6	104.3	_	_	38.4	_	54.7	_	_	°C/W
ΨЈТ	Junction-to-top characterization parameter	14.3	25.9	5.9	_	_	9.4	_	3.9	_	_	°C/W
ΨЈВ	Junction-to-board characterization parameter	55.4	35.5	102.6	_	_	38.1	_	53.9	_	_	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	_	_	_	_	8.68	_	_	_	_	_	°C/W

- For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report, SPRA953.
- (2) Maximum power dissipation is a function of T_{J(max)}, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_{J(max)} T_A) / θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7 (plastic) or MIL-STD-883 Method 1012 (ceramic).

6.5 TLC2272 and TLC2272A Electrical Characteristics $V_{DD} = 5 \text{ V}$

at specified free-air temperature, V_{DD} = 5 V; T_A = 25°C, unless otherwise noted.

	PARAMETER	TE	ST CONDITIONS	3	MIN	TYP	MAX	UNIT
			TLC2272	- T _A = 25°C		300	2500	
\/	Input offect valters	$V_{IC} = 0 \text{ V}, V_{DD\pm} = \pm 2.5 \text{ V},$	TLC2272A	1 _A = 25 C		300	950	\/
V _{IO}	Input offset voltage	$V_{O} = 0 \text{ V}, R_{S} = 50 \Omega$	TLC2272	Full Range ⁽¹⁾			3000	μV
			TLC2272A	- Full Range			1500	
α _{VIO}	Temperature coefficient of input offset voltage	$V_{IC} = 0 \text{ V}, V_{DD\pm} = \pm 2.5 \text{ V},$	$_{IC}$ = 0 V, $V_{DD\pm}$ = ±2.5 V, V_{O} = 0 V, R_{S} = 50 Ω			2		μV/°C
	Input offset voltage long-term drift ⁽²⁾	$V_{IC} = 0 \text{ V}, V_{DD\pm} = \pm 2.5 \text{ V}, V_{O} = 0 \text{ V}, R_{S} = 50 \Omega$				0.002		μV/mo
			All level parts	T _A = 25°C		0.5	60	
		$V_{IC} = 0 \text{ V}, V_{DD\pm} = \pm 2.5 \text{ V}, \\ V_{O} = 0 \text{ V}, R_{S} = 50 \Omega$	C level part	T _A = 0°C to 80°C			100	pA
I _{IO}	Input offset current		I level part	$T_A = -40$ °C to 85°C			150	
			Q level part	$T_A = -40^{\circ}C \text{ to } 125^{\circ}C$			800	
			M level part	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$			800	
			All level parts	T _A = 25°C		1	60	
			C level part	$T_A = 0$ °C to 80°C			100	
I _{IB}	Input bias current	$V_{IC} = 0 \text{ V}, V_{DD\pm} = \pm 2.5 \text{ V}, V_{O} = 0 \text{ V}, R_{S} = 50 \Omega$	I level part	$T_A = -40$ °C to 85°C			150	pА
		V0 = 0 V, NS = 00 12	Q level part	$T_A = -40^{\circ}\text{C to } 125^{\circ}\text{C}$			800	
			M level part	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$			800	
V	Common mode input valtage	D 50 0 1 1 1 5 5 7 1		T _A = 25°C	-0.3	2.5	4	V
V_{ICR}	$V_{\rm ICR}$ Common-mode input voltage $R_{\rm S} = 50 \ \Omega; V_{\rm IO} \le 5 \ mV$			Full Range ⁽¹⁾	0	2.5	3.5	V

⁽¹⁾ $T_A = -55^{\circ}C$ to 125°C.

⁽²⁾ Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at T_A = 150°C extrapolated to T_A = 25°C using the Arrhenius equation and assuming an activation energy of 0.96 eV.



TLC2272 and TLC2272A Electrical Characteristics $V_{DD} = 5 \text{ V}$ (continued)

at specified free-air temperature, V_{DD} = 5 V; T_A = 25°C, unless otherwise noted.

	PARAMETER		TEST CONDITION	IS	MIN	TYP	MAX	UNIT
		I _{OH} = -20 μA				4.99		
				T _A = 25°C	4.85	4.93		
/ _{OH}	High-level output voltage	I _{OH} = -200 μA		Full Range ⁽¹⁾	4.85			V
				T _A = 25°C	4.25	4.65		
		I _{OH} = −1 mA		Full Range ⁽¹⁾	4.25			
			I _{OL} = 50 μA			0.01		
			OL 11 P	T _A = 25°C		0.09	0.15	
V _{OL}	Low-level output voltage	V _{IC} = 2.5 V	$I_{OL} = 500 \mu A$	Full Range ⁽¹⁾			0.15	V
·OL		10 =10 1		T _A = 25°C		0.9	1.5	-
			$I_{OL} = 5 \text{ mA}$	Full Range ⁽¹⁾		0.0	1.5	
				$T_A = 25^{\circ}C$	15	35	1.0	
			C level part	$T_A = 0$ °C to 80°C	15	33		
						25		
		V _{IC} = 2.5 V,	I level part	T _A = 25°C	15	35		
	Large-signal differential	$V_0 = 1 \text{ V to 4 V};$		$T_A = -40$ °C to 85°C	15			
A_{VD}	voltage amplification	$R_L = 10 \text{ k}\Omega^{(3)}$	Q level part	T _A = 25°C	10	35		V/mV
				$T_A = -40^{\circ}C \text{ to } 125^{\circ}C$	10			
			M level part	T _A = 25°C	10	35]
			W lover part	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$	10			
		$V_{IC} = 2.5 \text{ V}, V_{O} = 1 \text{ V}$	to 4 V; $R_L = 1 M\Omega^{(3)}$			175		
r _{id}	Differential input resistance							Ω
r _i	Common-mode input resistance					10 ¹²		Ω
Ci	Common-mode input capacitance	f = 10 kHz, P package	f = 10 kHz. P package			8		pF
z _o	Closed-loop output impedance	f = 1 MHz, A _V = 10				140		Ω
0				T _A = 25°C	70	75		
CMRR	Common-mode rejection ratio	$V_{IC} = 0 \text{ V to 2.7 V},$ $V_{O} = 2.5 \text{ V}, R_{S} = 50 \Omega$		Full Range ⁽¹⁾	70			dB
	Constitution of the second of	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\		T _A = 25°C	80	95		
k _{SVR}	Supply-voltage rejection ratio $(\Delta V_{DD} / \Delta V_{IO})$	$V_{DD} = 4.4 \text{ V to } 16 \text{ V},$ $V_{IC} = V_{DD} / 2$, no load		Full Range ⁽¹⁾	80	33		dB
	(88 10)	10 00 , 1 111		$T_A = 25^{\circ}C$	00	2.2	3	
I_{DD}	Supply currrent	$V_O = 2.5 \text{ V}$, no load		Full Range ⁽¹⁾		2.2	3	mA
							<u> </u>	
SR	Slew rate at unity gain	$V_O = 0.5 \text{ V to } 2.5 \text{ V},$ $R_L = 10 \text{ k}\Omega^{(3)}, C_L = 10$	O pE(3)	$T_A = 25^{\circ}C$	2.3	3.6		V/µs
	· · · · · · · · · · · · · · · · · · ·		о рг 💛	Full Range ⁽¹⁾	1.7			
V_n	Equivalent input noise voltage	f = 10 Hz				50		nV/√H:
	· · · · · · · · · · · · · · · · · · ·	f = 1 kHz				9		
V_{NPP}	Peak-to-peak equivalent	f = 0.1 Hz to 1 Hz				1		μV
·NPP	input noise voltage	f = 0.1 Hz to 10 Hz				1.4		μ.
l _n	Equivalent input noise current					0.6		fA/√H:
				A _V = 1		0.0013%		
THD+N	Total harmonic distortion + noise	$V_0 = 0.5 \text{ V to } 2.5 \text{ V},$ $f = 20 \text{ kHz}, R_1 = 10 \text{ kG}$)(3)	A _V = 10		0.004%		
		$T = 20 \text{ KHZ}, K_L = 10 \text{ K}\Omega^{(0)}$		A _V = 100		0.03%		
	Gain-bandwidth product	$f = 10 \text{ kHz}, R_L = 10 \text{ k}\Omega^{(3)}, C_L = 100 \text{ pF}^{(3)}$				2.18		MHz
Вом	Maximum output-swing bandwidth	$V_{O(PP)} = 2 \text{ V}, A_V = 1, F$		00 pF ⁽³⁾		1		MHz
		$A_V = -1$, $R_L = 10 \text{ k}\Omega^{(3)}$		To 0.1%		1.5		
t _s	Settling time	Step = 0.5 V to 2.5 V,	, C _L = 100 pF ⁽³⁾	To 0.01%		2.6		μs
φ _m	Phase margin at unity gain	$R_L = 10 \text{ k}\Omega^{(3)}, C_L = 10$				50°		
T (1)	margin at army gain	$R_L = 10 \text{ k}\Omega^{(3)}, C_L = 100 \text{ p}F^{(3)}$ $R_L = 10 \text{ k}\Omega^{(3)}, C_L = 100 \text{ p}F^{(3)}$				10		dB

⁽³⁾ Referenced to 0 V.



6.6 TLC2272 and TLC2272A Electrical Characteristics $V_{DD\pm} = \pm 5 \text{ V}$

at specified free-air temperature, $V_{DD\pm} = \pm 5 \text{ V}$; $T_A = 25^{\circ}\text{C}$, unless otherwise noted.

	PARAMETER	1	EST CONDITION	S	MIN	TYP	MAX	UNIT
			TLC2272	T 25°C		300	2500	
V	land offert value as	$V_{IC} = 0 \text{ V}, V_{O} = 0 \text{ V},$	TLC2272A	T _A = 25°C		300	950	
V_{IO}	Input offset voltage	$R_S = 50 \Omega$	TLC2272	F. II D (1)			3000	μV
			TLC2272A	Full Range ⁽¹⁾			1500	
α_{VIO}	Temperature coefficient of input offset voltage	V _{IC} = 0 V, V _O = 0 V, R _S	= 50 Ω			2		μV/°C
	Input offset voltage long-term drift ⁽²⁾	V _{IC} = 0 V, V _O = 0 V, R _S	= 50 Ω			0.002		μV/mo
			All level parts	T _A = 25°C		0.5	60	
			C level part	T _A = 0°C to 80°C			100	
I_{IO}	Input offset current	$V_{IC} = 0 \text{ V}, V_{O} = 0 \text{ V},$ $R_{S} = 50 \Omega$	I level part	$T_A = -40$ °C to 85°C			150	pА
		1.3 00 11	Q level part	$T_A = -40$ °C to 125°C			800	
			M level part	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$			800	
			All level parts	T _A = 25°C		1	60	
			C level part	T _A = 0°C to 80°C			100	
I _{IB}	Input bias current	$V_{IC} = 0 \text{ V}, V_{O} = 0 \text{ V},$ $R_{S} = 50 \Omega$	I level part	$T_A = -40$ °C to 85°C			150	pА
		118 - 00 12	Q level part	$T_A = -40^{\circ}\text{C to } 125^{\circ}\text{C}$			800	
			M level part	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$			800	
		5 500 11/1 1 5 11		T _A = 25°C	-5.3	0	4	.,
V_{ICR}	Common-mode input voltage	$R_S = 50 \Omega; V_{IO} \le 5 \text{ mV}$		Full Range ⁽¹⁾	- 5	0	3.5	V
		I _O = -20 μA				4.99		
				T _A = 25°C	4.85	4.93		
V_{OM+}	Maximum positive peak	I _O = -200 μA		Full Range ⁽¹⁾	4.85			V
	output voltage			T _A = 25°C	4.25	4.65		
		I _O = −1 mA		Full Range ⁽¹⁾	4.25			
			I _O = 50 μA			-4.99		
		V _{IC} = 0 V,	Ι _Ο = 500 μΑ	T _A = 25°C	-4.85	-4.91		
V_{OM-}	Maximum negative peak output voltage			Full Range ⁽¹⁾	-4.85			V
	peak output voltage		I _O = 5 mA	T _A = 25°C	-3.5	-4.1		
				Full Range ⁽¹⁾	-3.5			
				T _A = 25°C	25	50		
			C level part	T _A = 0°C to 80°C	25			
				T _A = 25°C	25	50		
			I level part	$T_A = -40$ °C to 85°C	25			
A_{VD}	Large-signal differential voltage amplification	$V_O = \pm 4 \text{ V}; R_L = 10 \text{ k}\Omega$		T _A = 25°C	20	50		V/mV
	voltage amplification		Q level part	$T_A = -40^{\circ}C \text{ to } 125^{\circ}C$	20			
				T _A = 25°C	20	50		
			M level part	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$	20			
		$V_O = \pm 4 \text{ V}; R_L = 1 \text{ M}\Omega$	1			300		
r _{id}	Differential input resistance					10 ¹²		Ω
rį	Common-mode input resistance					10 ¹²		Ω
Ci	Common-mode input capacitance	f = 10 kHz, P package				8		pF
Z ₀	Closed-loop output impedance	f = 1 MHz, A _V = 10				130		Ω
		$V_{IC} = -5 \text{ V to } 2.7 \text{ V},$		T _A = 25°C	75	80		
CMRR	Common-mode rejection ratio	$V_0 = 0 \text{ V}, R_S = 50 \Omega$		Full Range ⁽¹⁾	75			dB
	Supply-voltage rejection ratio	Vpp. = 2 2 \/ to ±8 \/		T _A = 25°C	80	95		+
k_{SVR}	$(\Delta V_{DD} / \Delta V_{IO})$	$V_{IC} = 0$ V, no load	$V_{DD+} = 2.2 \text{ V to } \pm 8 \text{ V},$ $V_{IC} = 0 \text{ V, no load}$		80			dB
			Full Range ⁽¹⁾ T _A = 25°C		2.4	3		
I_{DD}	Supply currrent	$V_O = 0 V$, no load		Full Range ⁽¹⁾			3	mA

⁽¹⁾ $T_A = -55^{\circ}C$ to 125°C.

⁽²⁾ Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at T_A = 150°C extrapolated to T_A = 25°C using the Arrhenius equation and assuming an activation energy of 0.96 eV.



TLC2272 and TLC2272A Electrical Characteristics $V_{DD\pm} = \pm 5 \text{ V}$ (continued)

at specified free-air temperature, $V_{DD\pm} = \pm 5 \text{ V}$; $T_A = 25^{\circ}\text{C}$, unless otherwise noted.

	PARAMETER	TEST CONDITION	ONS	MIN	TYP	MAX	UNIT
SR	Clausesta at units sain	V _O = ±2.3 V,	T _A = 25°C	2.3	3.6		1//
SK	Slew rate at unity gain	$R_{L} = 10 \text{ k}\Omega, C_{L} = 100 \text{ pF}$	Full Range ⁽¹⁾	1.7			V/µs
V	Equivalent input pains valtage	f = 10 Hz	•		50		nV/√Hz
V _n	Equivalent input noise voltage	f = 1 kHz		9		nv/vHz	
V	Peak-to-peak equivalent	f = 0.1 Hz to 1 Hz		1		/	
V_{NPP}	input noise voltage	f = 0.1 Hz to 10 Hz		1.4		μV	
In	Equivalent input noise current				0.6		fA/√Hz
	Total harmonic distortion + noise		A _V = 1		0.0011%		
THD+N		$V_O = \pm 2.3$, $f = 20 \text{ kHz}$, $R_I = 10 \text{ k}\Omega$	A _V = 10		0.004%		
		7 = 20 Kt 12, Kt = 10 Kt2	A _V = 100		0.03%		
	Gain-bandwidth product	$f = 10 \text{ kHz}, R_L = 10 \text{ k}Ω, C_L = 100 \text{ pF}$	·		2.25		MHz
B _{OM}	Maximum output-swing bandwidth	$V_{O(PP)} = 4.6 \text{ V}, A_V = 1, R_L = 10 \text{ k}\Omega, C_L =$	100 pF		0.54		MHz
	Cottling time	$A_V = -1, R_L = 10 \text{ k}\Omega,$	To 0.1%		1.5		
t _s	Settling time	Step = $-2.\overline{3}$ V to 2.3 V, $C_L = 100$ pF	To 0.01%		3.2		μs
φ _m	Phase margin at unity gain	$R_L = 10 \text{ k}\Omega, C_L = 100 \text{ pF}$			52°		
	Gain margin	$R_L = 10 \text{ k}\Omega, C_L = 100 \text{ pF}$			10		dB

6.7 TLC2274 and TLC2274A Electrical Characteristics $V_{DD} = 5 \text{ V}$

at specified free-air temperature, $V_{DD} = 5 \text{ V}$; $T_A = 25^{\circ}\text{C}$, unless otherwise noted.

	PARAMETER	TE	ST CONDITION	S	MIN	TYP	MAX	UNIT
			TLC2274	T 0500		300	2500	
.,		$V_{IC} = 0 \text{ V}, V_{DD\pm} = \pm 2.5 \text{ V},$	TLC2274A	T _A = 25°C		300	950	.,
V _{IO}	Input offset voltage	$V_0 = 0 \text{ V}, R_S = 50 \Omega$	TLC2274	5 II D (1)			3000	μV
			TLC2274A	Full Range ⁽¹⁾			1500	
α_{VIO}	Temperature coefficient of input offset voltage	$V_{IC} = 0 \text{ V}, V_{DD\pm} = \pm 2.5 \text{ V},$	$V_0 = 0 \text{ V}, R_S = 50$	ο Ω		2		μV/°C
	Input offset voltage long-term drift ⁽²⁾	$V_{IC} = 0 \text{ V}, V_{DD\pm} = \pm 2.5 \text{ V},$	$V_{O} = 0 \text{ V}, R_{S} = 50$	Ο Ω		0.002		μV/mo
			All level parts	T _A = 25°C		0.5	60	
			C level part	$T_A = 0$ °C to 80°C			100	
I _{IO}	Input offset current	$V_{IC} = 0 \text{ V}, V_{DD\pm} = \pm 2.5 \text{ V}, V_{O} = 0 \text{ V}, R_{S} = 50 \Omega$	I level part	$T_A = -40$ °C to 85°C			150	pА
		$V_0 = 0 \text{ V}, R_S = 50 \Omega$	Q level part	$T_A = -40^{\circ}\text{C to } 125^{\circ}\text{C}$			800	
			M level part	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$			800	
			All level parts	T _A = 25°C		1	60	
			C level part	T _A = 0°C to 80°C			100	
I _{IB}	Input bias current	$V_{IC} = 0 \text{ V}, V_{DD\pm} = \pm 2.5 \text{ V}, V_{O} = 0 \text{ V}, R_{S} = 50 \Omega$	I level part	$T_A = -40$ °C to 85°C			150	pА
		V0 = 0 V, NS = 00 12	Q level part	$T_A = -40^{\circ}\text{C to } 125^{\circ}\text{C}$			800	
			M level part	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$			800	
.,	O	D 50 0: 11/ 1 < 5 == 1/		T _A = 25°C	-0.3	2.5	4	V
V _{ICR}	Common-mode input voltage	$R_S = 50 \Omega$; $ V_{IO} \le 5 \text{ mV}$		Full Range ⁽¹⁾	0	2.5	3.5	V
		I _{OH} = -20 μA				4.99		
		I 200A		T _A = 25°C	4.85	4.93		
V_{OH}	High-level output voltage	I _{OH} = -200 μA		Full Range ⁽¹⁾	4.85			V
		1 4 4		T _A = 25°C	4.25	4.65		
		I _{OH} = −1 mA		Full Range ⁽¹⁾	4.25			

⁽¹⁾ $T_A = -55^{\circ}C$ to 125°C.

⁽²⁾ Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at T_A = 150°C extrapolated to T_A = 25°C using the Arrhenius equation and assuming an activation energy of 0.96 eV.



TLC2274 and TLC2274A Electrical Characteristics $V_{DD} = 5 \text{ V}$ (continued)

at specified free-air temperature, $V_{DD} = 5 \text{ V}$; $T_A = 25^{\circ}\text{C}$, unless otherwise noted.

	PARAMETER	TI	EST CONDITION	IS	MIN	TYP	MAX	UNIT
			I _{OL} = 50 μA			0.01		
			I 500 ··· A	T _A = 25°C		0.09	0.15	
V_{OL}	Low-level output voltage	V _{IC} = 2.5 V	$I_{OL} = 500 \mu A$	Full Range ⁽¹⁾			0.15	V
				T _A = 25°C		0.9	1.5	
			$I_{OL} = 5 \text{ mA}$	Full Range ⁽¹⁾			1.5	
			C lavel part	T _A = 25°C	15	35		
			C level part	$T_A = 0$ °C to 80°C	15			
			Llovel nert	T _A = 25°C	15	35		
		$V_{IC} = 2.5 \text{ V}, V_{O} = 1 \text{ V to}$	I level part	$T_A = -40$ °C to 85°C	15			
A_{VD}	Large-signal differential voltage amplification	$R_L = 10 \text{ k}\Omega^{(3)}$	O lovel part	T _A = 25°C	10	35		V/mV
	vollage amplification		Q level part	$T_A = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	10			
			M lovel port	T _A = 25°C	10	35		
			M level part	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$	10			
		$V_{IC} = 2.5 \text{ V}, V_{O} = 1 \text{ V to } 4$	$V; R_L = 1 M\Omega^{(3)}$			175		
r _{id}	Differential input resistance					10 ¹²		Ω
r _i	Common-mode input resistance					10 ¹²		Ω
c _i	Common-mode input capacitance	f = 10 kHz, P package				8		pF
Z _o	Closed-loop output impedance	f = 1 MHz, A _V = 10				140		Ω
CMDD	Commence and a selection and	V _{IC} = 0 V to 2.7 V,		70	75		5	
CMRR	Common-mode rejection ratio	$V_0 = 2.5 \text{ V}, R_S = 50 \Omega$		Full Range ⁽¹⁾	70			dB
l.	Supply-voltage rejection ratio	V _{DD} = 4.4 V to 16 V,		T _A = 25°C	80	95		40
k _{SVR}	$(\Delta V_{DD} / \Delta V_{IO})$	$V_{IC} = V_{DD} / 2$, no load		Full Range ⁽¹⁾	80			dB
	Cupply ourrent	V _O = 2.5 V, no load		T _A = 25°C		4.4	6	mA
I _{DD}	Supply currrent	v _O = 2.5 v, 110 10au		Full Range ⁽¹⁾			6	IIIA
SR	Slew rate at unity gain	$V_O = 0.5 \text{ V to } 2.5 \text{ V},$ $R_L = 10 \text{ k}\Omega^{(3)}, C_L = 100 \text{ p}$		T _A = 25°C	2.3	3.6		V/µs
SK	Siew rate at unity gain	$R_L = 10 \text{ k}\Omega^{(3)}, C_L = 100 \text{ p}$	F ⁽³⁾	Full Range ⁽¹⁾	1.7			v/μs
V	Equivalent input paige valters	f = 10 Hz				50		nV/√Hz
V _n	Equivalent input noise voltage	f = 1 kHz				9		IIV/ VIIZ
V	Peak-to-peak equivalent	f = 0.1 Hz to 1 Hz				1		μV
V_{NPP}	input noise voltage	f = 0.1 Hz to 10 Hz				1.4		μν
In	Equivalent input noise current					0.6		fA/√Hz
				A _V = 1		0.0013%		
THD+N	Total harmonic distortion + noise	$V_O = 0.5 \text{ V to } 2.5 \text{ V},$ $f = 20 \text{ kHz}, R_L = 10 \text{ k}\Omega^{(3)}$		A _V = 10		0.004%		
				A _V = 100		0.03%		
	Gain-bandwidth product	$f = 10 \text{ kHz}, R_L = 10 \text{ k}\Omega^{(3)}$				2.18		MHz
B _{OM}	Maximum output-swing bandwidth	$V_{O(PP)} = 2 \text{ V}, A_V = 1, R_L =$	00 pF ⁽³⁾		1		MHz	
t _s	Settling time	$A_V = -1$, $R_L = 10 \text{ k}\Omega^{(3)}$,	–/2\	To 0.1%		1.5		μs
-S	· · · · · · · · · · · · · · · · ·	Step = 0.5 V to 2.5 V, C _L		2.6		μ0		
ϕ_{m}	Phase margin at unity gain	$R_L = 10 \text{ k}\Omega^{(3)}, C_L = 100 \text{ p}$				50°		
	Gain margin	$R_L = 10 \text{ k}\Omega^{(3)}, C_L = 100 \text{ p}$	F ⁽³⁾			10		dB

⁽³⁾ Referenced to 0 V.



6.8 TLC2274 and TLC2274A Electrical Characteristics $V_{DD\pm} = \pm 5 \text{ V}$

at specified free-air temperature, $V_{DD+} = \pm 5 \text{ V}$; $T_A = 25^{\circ}\text{C}$, unless otherwise noted.

	PARAMETER	T	EST CONDITION	S	MIN	TYP	MAX	UNIT
			TLC2274	T 0500		300	2500	
.,	land offertualtens	$V_{IC} = 0 \text{ V}, V_{O} = 0 \text{ V},$	TLC2274A	T _A = 25°C		300	950	
V_{IO}	Input offset voltage	$R_S = 50 \Omega$	TLC2274	F. II Danas (1)			3000	μV
			TLC2274A	Full Range ⁽¹⁾			1500	
α_{VIO}	Temperature coefficient of input offset voltage	V _{IC} = 0 V, V _O = 0 V, R _S =	= 50 Ω			2		μV/°C
	Input offset voltage long-term drift ⁽²⁾	V _{IC} = 0 V, V _O = 0 V, R _S =	= 50 Ω			0.002		μV/mo
			All level parts	T _A = 25°C		0.5	60	
			C level part	T _A = 0°C to 80°C			100	
I _{IO}	Input offset current	$V_{IC} = 0 \text{ V}, V_{O} = 0 \text{ V},$ $R_{S} = 50 \Omega$	I level part	$T_A = -40$ °C to 85°C			150	pА
		113 = 30 12	Q level part	$T_A = -40^{\circ}\text{C to } 125^{\circ}\text{C}$			800	
			M level part	$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$			800	
			All level parts	T _A = 25°C		1	60	
			C level part	T _A = 0°C to 80°C			100	
I _{IB}	Input bias current	$V_{IC} = 0 \text{ V}, V_{O} = 0 \text{ V},$	I level part	$T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C}$			150	pА
.5	·	$R_S = 50 \Omega$	Q level part	T _A = -40°C to 125°C			800	•
			M level part	$T_A = -55^{\circ}\text{C to } 125^{\circ}\text{C}$			800	
				T _A = 25°C	-5.3	0	4	
V_{ICR}	Common-mode input voltage	$R_S = 50 \Omega$; $ V_{IO} \le 5 \text{ mV}$		Full Range ⁽¹⁾	-5	0	3.5	V
		I _O = -20 μA		. a rango		4.99	0.0	
		10 - 20 μ/τ		T _A = 25°C	4.85	4.93		
V	Maximum positive peak	I _O = -200 μA		Full Range ⁽¹⁾	4.85	4.55		V
V OM+	output voltage			T _A = 25°C	4.25	4.65		v
		$I_O = -1 \text{ mA}$		Full Range ⁽¹⁾	4.25	4.00		
			I = 50 HA	Tuli Range	4.20	-4.99		
			I _O = 50 μA	T _A = 25°C	-4.85	-4.99 -4.91		
\/	Maximum negative peak	V _{IC} = 0 V	I _O = 500 μA	Full Range ⁽¹⁾	-4.85	-4.31		V
V_{OM-}	output voltage	V _{IC} = U V		_		4.4		V
			$I_O = 5 \text{ mA}$	T _A = 25°C Full Range ⁽¹⁾	-3.5	-4.1		
					-3.5			
			C level part	T _A = 25°C	25	50		
				$T_A = 0$ °C to 80°C	25			
			I level part	T _A = 25°C	25	50		
	Large-signal differential	$V_{O} = \pm 4 \text{ V}; R_{L} = 10 \text{ k}\Omega$		$T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C}$	25			.,, .,
A_{VD}	voltage amplification		Q level part	T _A = 25°C	20	50		V/mV
				$T_A = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	20			
			M level part	T _A = 25°C	20	50		
				$T_A = -55^{\circ}C \text{ to } 125^{\circ}C$	20			
		$V_O = \pm 4 \text{ V}; R_L = 1 \text{ M}\Omega$				300		
r _{id}	Differential input resistance					10 ¹²		Ω
rį	Common-mode input resistance					10 ¹²		Ω
Ci	Common-mode input capacitance	f = 10 kHz, P package				8		pF
Z _O	Closed-loop output impedance	$f = 1 \text{ MHz}, A_V = 10$				130		Ω
CMDD	Common mode rejection ratio	$V_{IC} = -5 \text{ V to } 2.7 \text{ V},$		$T_A = 25^{\circ}C$	75	80		dB
CMRR	Common-mode rejection ratio	$V_O = 0 \text{ V}, R_S = 50 \Omega$		Full Range ⁽¹⁾	75			UB
l.	Supply-voltage rejection ratio	$V_{DD+} = 2.2 \text{ V to } \pm 8 \text{ V},$		T _A = 25°C	80	95		٩Ľ
k _{SVR}	$(\Delta V_{DD} / \Delta V_{IO})$	$V_{IC} = 0 \text{ V, no load}$		Full Range ⁽¹⁾	80			dB
-		V _O = 0 V, no load	T _A = 25°C		4.8	6		
I_{DD}	Supply currrent							mA

⁽¹⁾ $T_A = -55^{\circ}C$ to 125°C.

⁽²⁾ Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at T_A = 150°C extrapolated to T_A = 25°C using the Arrhenius equation and assuming an activation energy of 0.96 eV.



TLC2274 and TLC2274A Electrical Characteristics $V_{DD\pm} = \pm 5 \text{ V}$ (continued)

at specified free-air temperature, $V_{DD\pm} = \pm 5 \text{ V}$; $T_A = 25^{\circ}\text{C}$, unless otherwise noted.

	PARAMETER	TEST CONDITIO	NS	MIN	TYP	MAX	UNIT
CD.	Clausesta at unity sain	V _O = ±2.3 V,	T _A = 25°C	2.3	3.6		1////
SR	Slew rate at unity gain	$R_L = 10 \text{ k}\Omega, C_L = 100 \text{ pF}$	1.7			V/µs	
V	Equivalent input paige valtage	f = 10 Hz			50		nV/√Hz
V _n	Equivalent input noise voltage	f = 1 kHz			9		nv/√Hz
	Peak-to-peak equivalent	f = 0.1 Hz to 1 Hz			1		\/
V_{NPP}	input noise voltage	f = 0.1 Hz to 10 Hz			1.4		μV
In	Equivalent input noise current				0.6		fA/√Hz
			A _V = 1		0.0011%		
THD+N	Total harmonic distortion + noise	$V_O = \pm 2.3$, $f = 20 \text{ kHz}$, $R_1 = 10 \text{ k}\Omega$	A _V = 10		0.004%		
		1 - 20 M 12, M - 10 M2	A _V = 100		0.03%		
	Gain-bandwidth product	$f = 10 \text{ kHz}, R_L = 10 \text{ k}Ω, C_L = 100 \text{ pF}$	·		2.25		MHz
B _{OM}	Maximum output-swing bandwidth	$V_{O(PP)} = 4.6 \text{ V}, A_V = 1, R_L = 10 \text{ k}\Omega, C_L =$	100 pF		0.54		MHz
	Catalia a tima	$A_{V} = -1$, $R_{I} = 10 \text{ k}\Omega$,	To 0.1%		1.5		
t _s	Settling time	Step = -2.3 V to 2.3 V, $C_L = 100$ pF	To 0.01%		3.2		μs
φ _m	Phase margin at unity gain	$R_L = 10 \text{ k}\Omega, C_L = 100 \text{ pF}$		52°			
	Gain margin	$R_L = 10 \text{ k}\Omega, C_L = 100 \text{ pF}$		10		dB	

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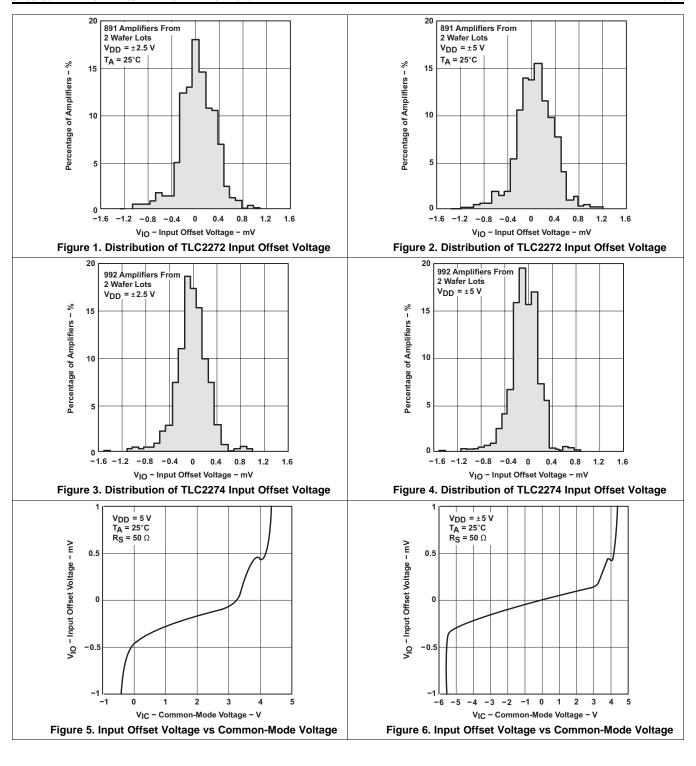
6.9 Typical Characteristics

Table 1. Table of Graphs

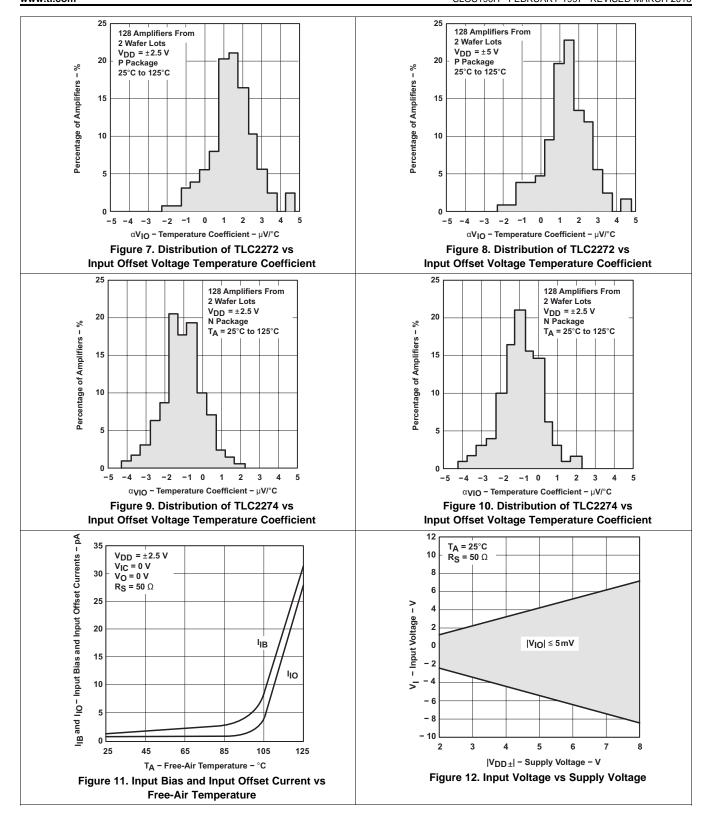
			FIGURE ⁽¹⁾
.,	lanut offeet veltere	Distribution	1, 2, 3, 4
/ ₁₀	Input offset voltage	vs Common-mode voltage	5, 6
t _{VIO}	Input offset voltage temperature coefficient	Distribution	7, 8, 9, 10 ⁽²⁾
_{IB} /I _{IO}	Input bias and input offset current	vs Free-air temperature	11 ⁽²⁾
,	land with an	vs Supply voltage	12
/ _I	Input voltage	vs Free-air temperature	13 ⁽²⁾
/ _{OH}	High-level output voltage	vs High-level output current	14 ⁽²⁾
/ _{OL}	Low-level output voltage	vs Low-level output current	15, 16 ⁽²⁾
/ _{OM+}	Maximum positive peak output voltage	vs Output current	17 ⁽²⁾
/ _{OM-}	Maximum negative peak output voltage	vs Output current	18 ⁽²⁾
/ _{O(PP)}	Maximum peak-to-peak output voltage	vs Frequency	19
<u> </u>		vs Supply voltage	20
os	Short-circuit output current	vs Free-air temperature	21(2)
V ₀	Output voltage	vs Differential input voltage	22, 23
	Large-signal differential voltage amplification	vs Load resistance	24
A_{VD}	Large-signal differential voltage amplification and phase margin	vs Frequency	25, 26
V D	Large-signal differential voltage amplification	vs Free-air temperature	27 ⁽²⁾ , 28 ⁽²⁾
<u>7</u> 0	Output impedance	vs Frequency	29, 30
		vs Frequency	31
CMRR	Common-mode rejection ratio	vs Free-air temperature	32
		vs Frequency	33, 34
SVR	Supply-voltage rejection ratio	vs Free-air temperature	35 ⁽²⁾
		vs Supply voltage	36 ⁽²⁾ , 37 ⁽²⁾
DD	Supply current	vs Free-air temperature	38 ⁽²⁾ , 39 ⁽²⁾
		vs Load Capacitance	40
SR	Slew rate	vs Free-air temperature	41 ⁽²⁾
	Inverting large-signal pulse response	To the same temperature	42, 43
	Voltage-follower large-signal pulse response		44, 45
/ ₀	Inverting small-signal pulse response		46, 47
	Voltage-follower small-signal pulse response		48, 49
/ _n	Equivalent input noise voltage	vs Frequency	50, 51
	Noise voltage over a 10-second period	- 11-2 - 27	52
	Integrated noise voltage	vs Frequency	53
HD+N	Total harmonic distortion + noise	vs Frequency	54
		vs Supply voltage	55
	Gain-bandwidth product	vs Free-air temperature	56 ⁽²⁾
P _m	Phase margin	vs Load capacitance	57
riii	Gain margin	vs Load capacitance	58

For all graphs where $V_{DD} = 5 \text{ V}$, all loads are referenced to 2.5 V. Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

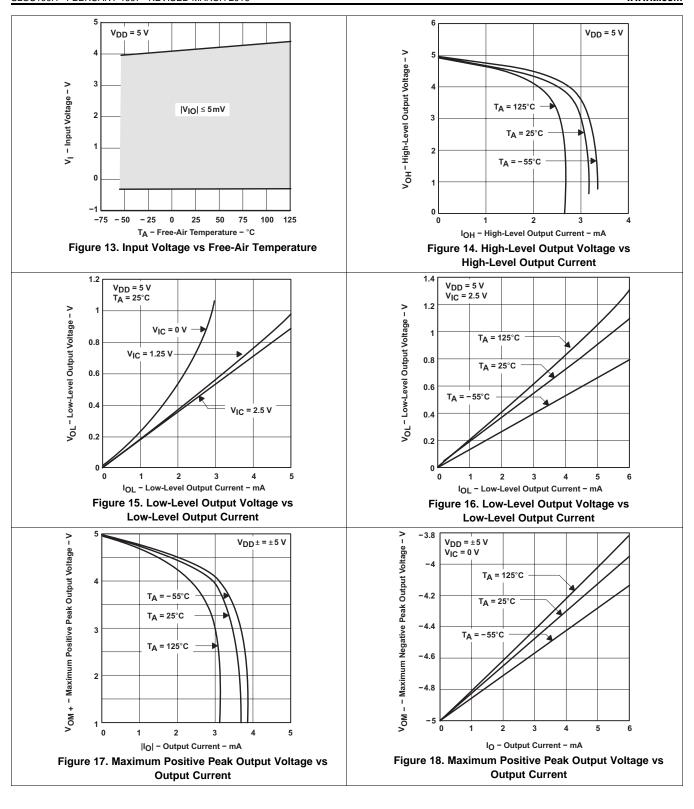




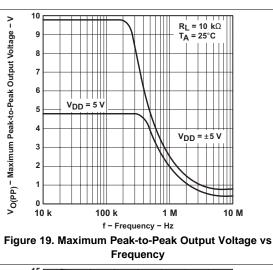












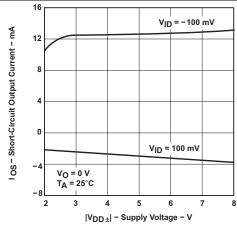
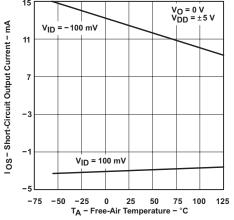


Figure 20. Short-Circuit Output Current vs Supply Voltage



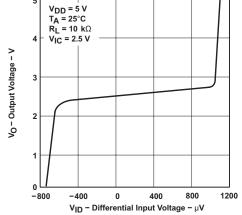
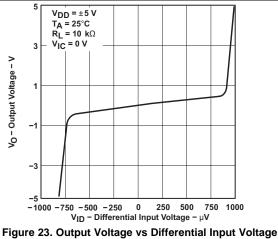


Figure 21. Short-Circuit Output Current vs Free-Air Temperature

Figure 22. Output Voltage vs Differential Input Voltage



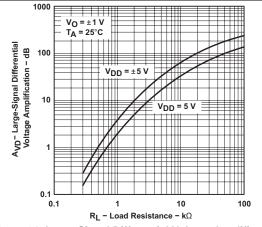
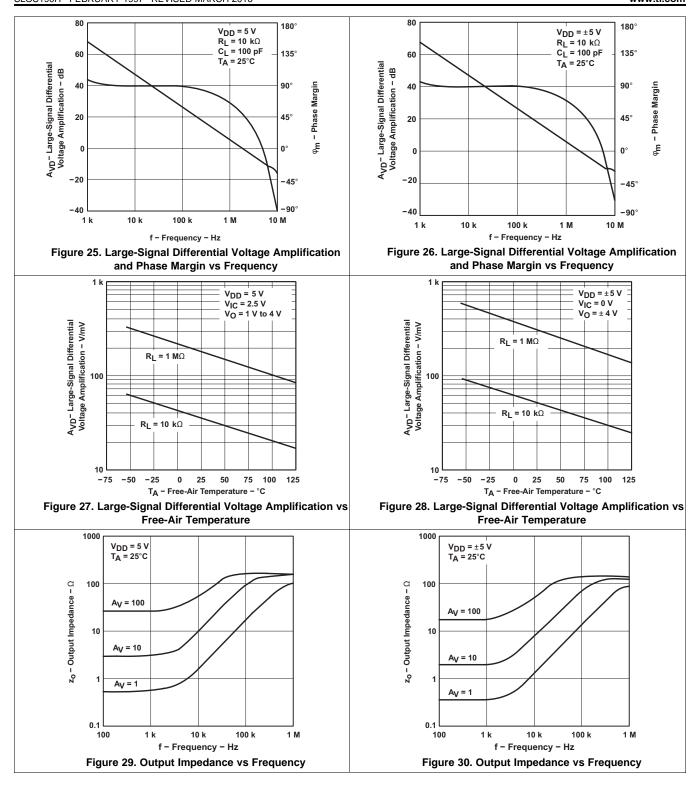
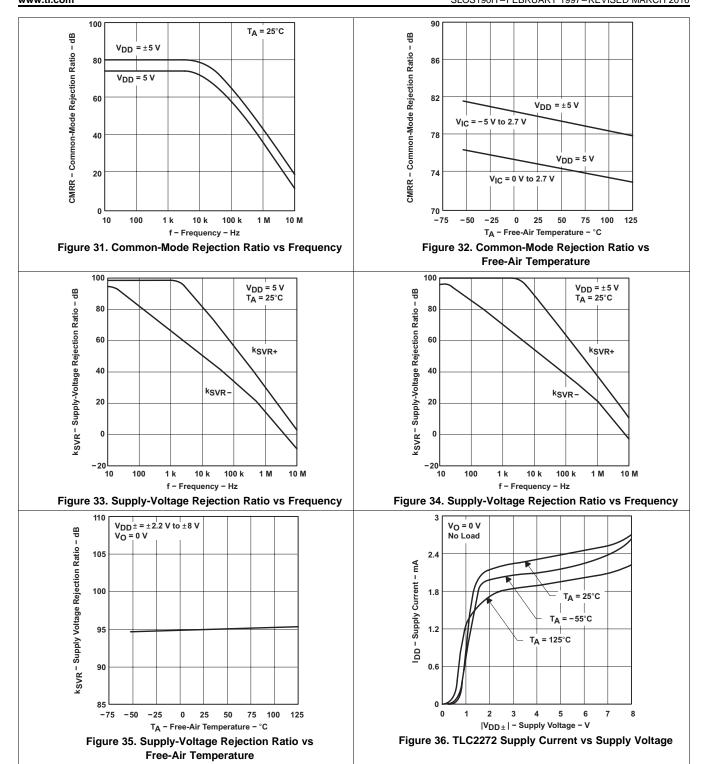


Figure 24. Large-Signal Differential Voltage Amplification vs **Load Resistance**

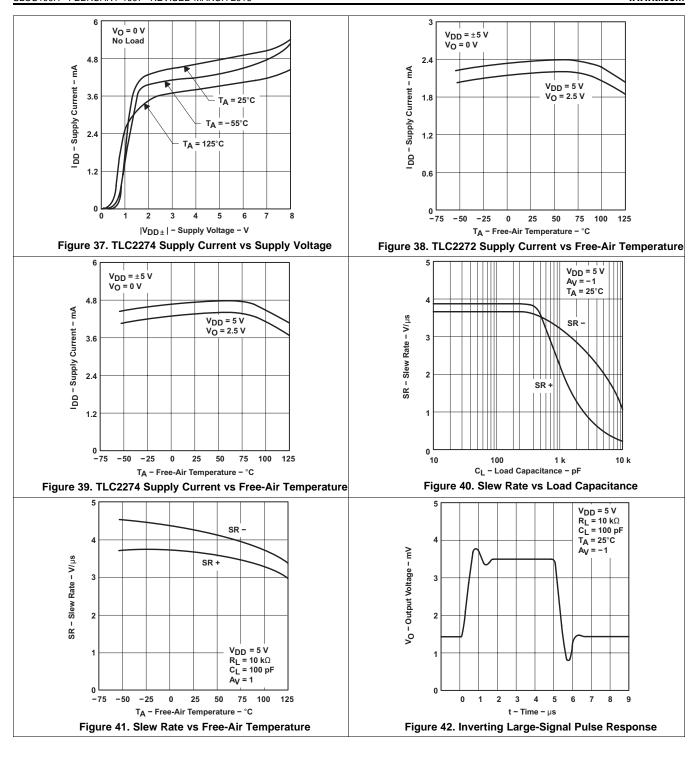




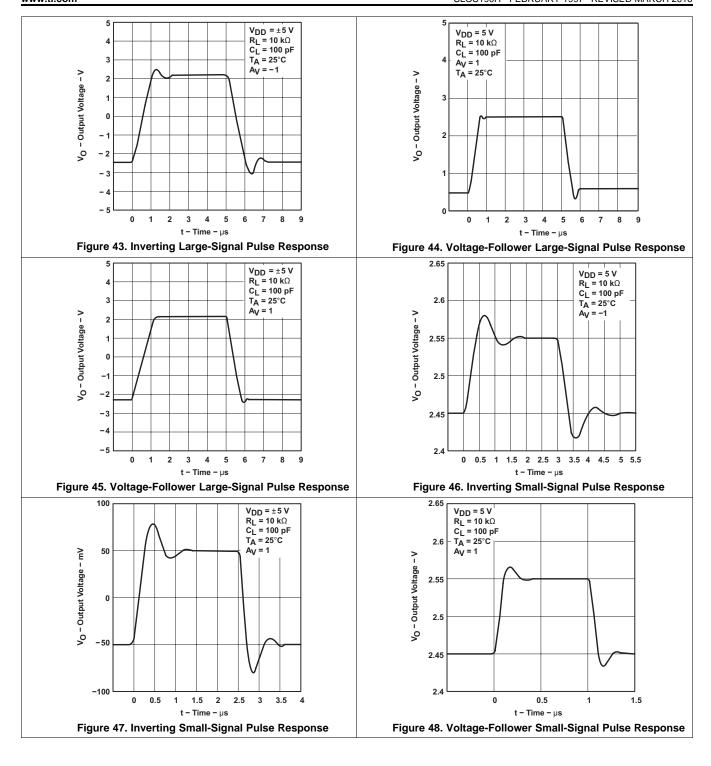




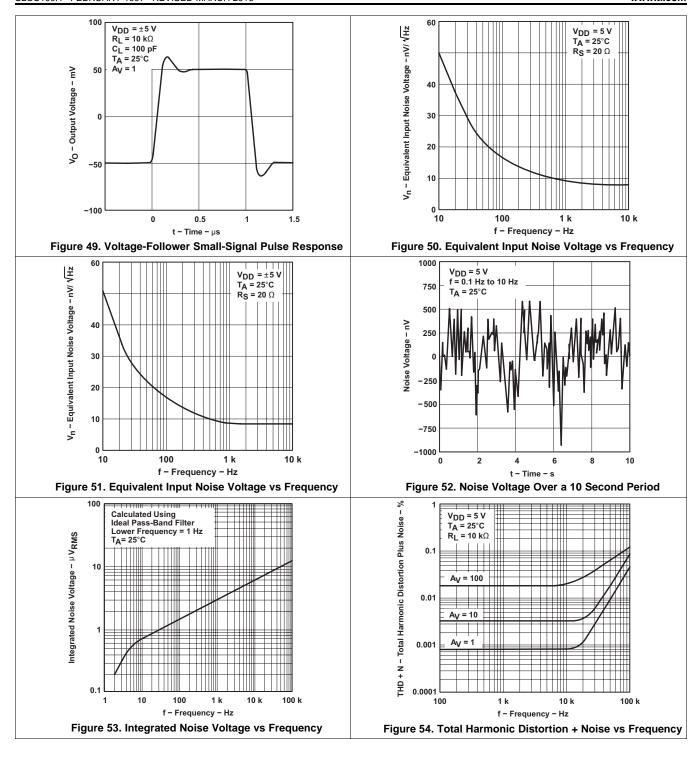




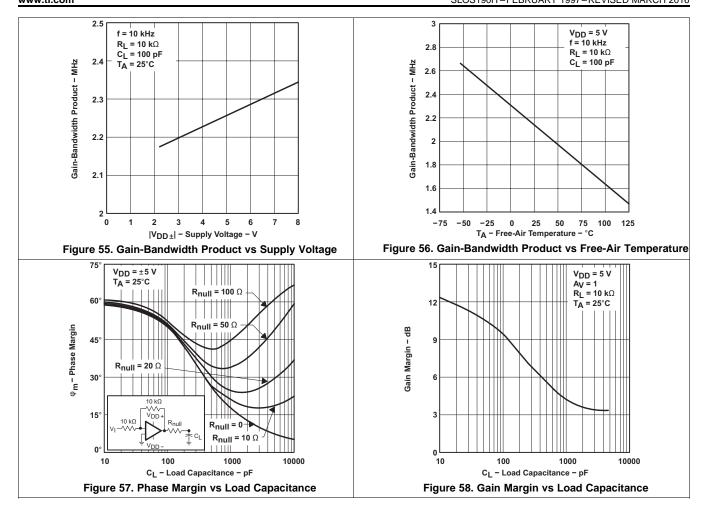














7 Detailed Description

7.1 Overview

The TLC227x and TLC227xA families of devices are rail-to-rail output operational amplifiers. These devices operate from 4.4-V to 16-V single supply and ±2.2-V ±8-V dual supply, are unity-gain stable, and are suitable for a wide range of general-purpose applications.

7.2 Functional Block Diagram

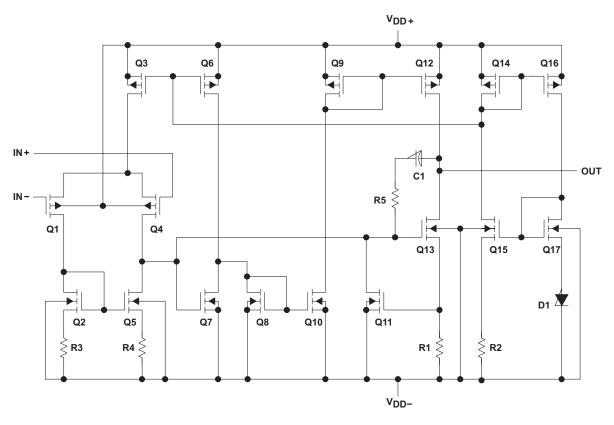


Table 2. Device Component Count⁽¹⁾

Component	TLC2272	TLC2274
Transistors	38	76
Resistors	26	52
Diodes	9	18
Capacitors	3	6

(1) Includes both amplifiers and all ESD, bias, and trim circuitry.

7.3 Feature Description

The TLC227xA family of devices feature 2-MHz bandwidth and voltage noise of 9 nV/√Hz with performance rated from 4.4 V to 16 V across an automotive temperature range (–40°C to 125°C). LinMOS suits a wide range of audio, automotive, industrial, and instrumentation applications.

7.4 Device Functional Modes

The TLC227xA families of devices is powered on when the supply is connected. The devices may operate with single or dual supply, depending on the application. The devices are in its full performance once the supply is above the recommended value.

Submit Documentation Feedback



8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

8.1.1 Macromodel Information

Macromodel information provided was derived using MicroSim PartsTM, the model generation software used with MicroSim PSpiceTM. The Boyle macromodel ⁽¹⁾ and subcircuit in Figure 59 were generated using the TLC227x typical electrical and operating characteristics at $T_A = 25^{\circ}C$. Using this information, output simulations of the following key parameters can be generated to a tolerance of 20% (in most cases):

- Maximum positive output voltage swing
- · Maximum negative output voltage swing
- · Slew rate
- Quiescent power dissipation
- Input bias current
- Open-loop voltage amplification
- Unity gain frequency
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- · Short-circuit output current limit

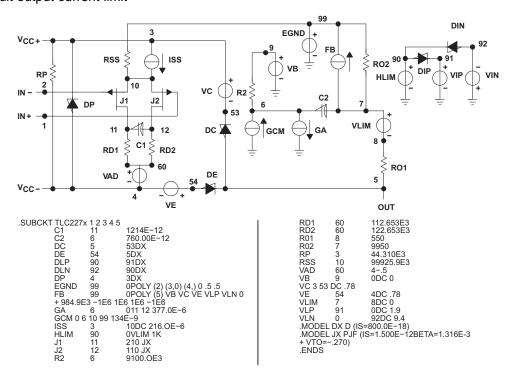


Figure 59. Boyle Macromodel and Subcircuit

(1) Macromodeling of Integrated Circuit Operational Amplifiers, IEEE Journal of Solid-State Circuits, SC-9, 353 (1974).



8.2 Typical Application

8.2.1 High-Side Current Monitor

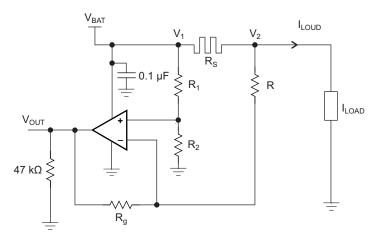


Figure 60. Equivalent Schematic (Each Amplifier)

8.2.1.1 Design Requirements

For this design example, use the parameters listed in Table 3 as the input parameters.

Table 3. Design Parameters

	PARAMETER	VALUE
V_{BAT}	Battery Voltage	12 V
R _{SENSE}	Sense Resistor	0.1 Ω
I _{LOAD}	Load Current	0 A to 10 A
	Operational Amplifier	Set in Differential configuration with Gain = 10

8.2.1.2 Detailed Design Procedure

This circuit is designed for measuring the high-side current in automotive body control modules with 12-V battery or similar applications. The operational amplifier is set as differential with an external resistor network.

8.2.1.2.1 Differential Amplifier Equations

Equation 1 and Equation 2 are used to calculate V_{OUT}.

$$V_{OUT} = \frac{R_g}{R} \left(\frac{\frac{R}{R_g} - \frac{R_1}{R_2}}{1 + \frac{R_1}{R_2}} \times \frac{V_1 + V_2}{2} + \frac{1 + \frac{1}{2} \left(\frac{R_1}{R_2} + \frac{R}{R_g} \right)}{1 + \frac{R_1}{R_2}} (V_1 - V_2) \right)$$

$$V_{OUT} = \frac{R_g}{R} \left(\frac{\frac{R}{R_g} - \frac{R_1}{R_2}}{1 + \frac{R_1}{R_2}} \times V_{BAT} + \frac{1 + \frac{1}{2} \left(\frac{R_1}{R_2} + \frac{R}{R_g} \right)}{1 + \frac{R_1}{R_2}} \times R_S \times I_{Load} \right)$$

$$(1)$$

In an ideal case $R_1 = R$ and $R_2 = R_g$, and V_{OUT} can then be calculated using Equation 3:

$$V_{OUT} = \frac{R_g}{R} \times R_S \times I_{Load}$$
 (3)



However, as the resistors have tolerances, they cannot be perfectly matched.

$$R_1 = R \pm \Delta R_1$$

$$R_2 = R_2 \pm \Delta R_2$$

$$R = R \pm \Delta R$$

$$R_g = R_g \pm \Delta R_g$$

$$Tol = \frac{DR}{R}$$

 $OI = \frac{}{R}$ (4)

By developing the equations and neglecting the second order, the worst case is when the tolerances add up. This is shown by Equation 5.

$$V_{OUT} = \pm (4 \text{ ToI}) \frac{R_g}{R + R_g} \times V_{BAT} + \left(1 \pm 2 \text{ ToI} \left(1 + \frac{2R}{R + R_g}\right)\right) \frac{R_g}{R} \times R_S \times I_{LOAD}$$

where

- Tol = 0.01 for 1%
- Tol = 0.001 for 0.1%

If the resistors are perfectly matched, then ToI = 0 and V_{OUT} is calculated using Equation 6.

$$V_{OUT} = \frac{R_g}{R} \times R_S \times I_{LOAD}$$
 (6)

The highest error is from the Common mode, as shown in Equation 7.

$$4 (ToI) \frac{R_g}{R + R_g} \times V_{BAT}$$
 (7)

Gain of 10, R_q / R = 10, and Tol = 1%:

Common mode error = $((4 \times 0.01) / 1.1) \times 12 \text{ V} = 0.436 \text{ V}$

Gain of 10 and Tol = 0.1%:

Common mode error = 43.6 mV

The resistors were chosen from 2% batches.

 R_1 and R 12 $k\Omega$

 R_2 and R_α 120 k Ω

Ideal Gain = 120 / 12 = 10

The measured value of the resistors:

 $R_1 = 11.835 \text{ k}\Omega$

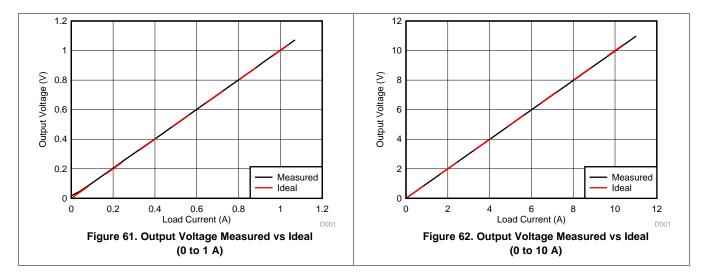
 $R = 11.85 k\Omega$

 $R_2 = 117.92 \text{ k}\Omega$

 $R_q = 118.07 \text{ k}\Omega$



8.2.1.3 Application Curves



9 Power Supply Recommendations

Supply voltage for a single supply is from 4.4 V to 16 V, and from ±2.2 V to ±8 V for dual supply. In the high-side sensing application, the supply is connected to a 12-V battery.

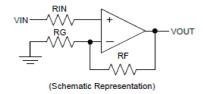


10 Layout

10.1 Layout Guidelines

The TLC227x and TLC227xA families of devices are wideband amplifiers. To realize the full operational performance of the devices, good high-frequency printed-circuit-board (PCB) layout practices are required. Low-loss 0.1-µF bypass capacitors must be connected between each supply pin and ground as close to the device as possible. The bypass capacitor traces should be designed for minimum inductance.

10.2 Layout Example



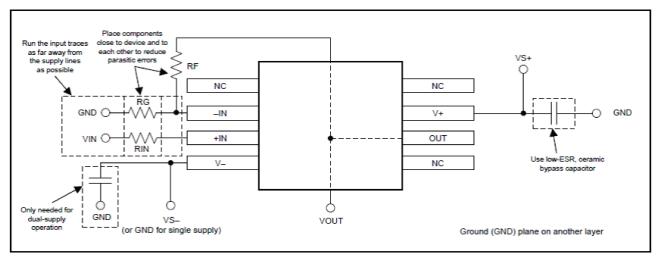


Figure 63. Layout Example



11 Device and Documentation Support

11.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 4. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
TLC2272	Click here	Click here	Click here	Click here	Click here
TLC2272A	Click here	Click here	Click here	Click here	Click here
TLC2272M	Click here	Click here	Click here	Click here	Click here
TLC2272AM	Click here	Click here	Click here	Click here	Click here
TLC2274	Click here	Click here	Click here	Click here	Click here
TLC2274A	Click here	Click here	Click here	Click here	Click here
TLC2274M	Click here	Click here	Click here	Click here	Click here
TLC2274AM	Click here	Click here	Click here	Click here	Click here

11.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.3 Trademarks

E2E is a trademark of Texas Instruments.

MicroSim Parts, PSpice are trademarks of MicroSim.

All other trademarks are the property of their respective owners.

11.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.5 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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25-Oct-2016

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9318201M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9318201M2A TLC2274 MFKB	Samples
5962-9318201MCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9318201MC A TLC2274MJB	Samples
5962-9318201QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9318201QD A TLC2274MWB	Samples
5962-9318202Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9318202Q2A TLC2274 AMFKB	Samples
5962-9318202QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9318202QC A TLC2274AMJB	Samples
5962-9318202QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9318202QD A TLC2274AMWB	Samples
5962-9555201NXD	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	Q2272M	Samples
5962-9555201NXDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	Q2272M	Samples
5962-9555201Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9555201Q2A TLC2272 MFKB	Samples
5962-9555201QHA	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type	-55 to 125	9555201QHA TLC2272M	Samples
5962-9555201QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9555201QPA TLC2272M	Samples
5962-9555202Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9555202Q2A TLC2272 AMFKB	Samples





Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
	(1)				Qty	(2)	(6)	(3)		(4/5)	
5962-9555202QHA	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type	-55 to 125	9555202QHA TLC2272AM	Sample
5962-9555202QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9555202QPA TLC2272AM	Sample
TLC2272ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272AC	Sample
TLC2272ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272AC	Sample
TLC2272ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272AC	Sample
TLC2272ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272AC	Sample
TLC2272ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC2272AC	Sampl
TLC2272ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC2272AC	Sampl
TLC2272ACPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		P2272A	Sampl
TLC2272ACPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		P2272A	Sampl
TLC2272ACPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI			
TLC2272ACPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		P2272A	Sampl
TLC2272ACPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		P2272A	Sampl
TLC2272AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272AI	Sampl
TLC2272AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272AI	Sampl
TLC2272AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272AI	Samp
TLC2272AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272AI	Samp
TLC2272AIP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC2272AI	Samp





Orderable Device	Status	Package Type	_	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TLC2272AIPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC2272AI	Samples
TLC2272AMD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2272AM	Samples
TLC2272AMDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272AM	Samples
TLC2272AMDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2272AM	Samples
TLC2272AMDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272AM	Samples
TLC2272AMFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9555202Q2A TLC2272 AMFKB	Samples
TLC2272AMJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9555202QPA TLC2272AM	Samples
TLC2272AMP	OBSOLET	E PDIP	Р	8		TBD	Call TI	Call TI	-55 to 125		
TLC2272AMUB	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type	-55 to 125	9555202QHA TLC2272AM	Samples
TLC2272AQD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C2272A	Samples
TLC2272AQDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		C2272A	Samples
TLC2272AQDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C2272A	Samples
TLC2272AQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		C2272A	Samples
TLC2272CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2272C	Samples
TLC2272CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2272C	Samples
TLC2272CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2272C	Samples
TLC2272CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2272C	Samples



Orderable Device		Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TLC2272CP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TLC2272CP	Samples
TLC2272CPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TLC2272CP	Samples
TLC2272CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P2272	Samples
TLC2272CPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P2272	Samples
TLC2272CPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P2272	Samples
TLC2272CPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	0 to 70		
TLC2272CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P2272	Samples
TLC2272CPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P2272	Samples
TLC2272ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		22721	Samples
TLC2272IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		22721	Samples
TLC2272IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		22721	Samples
TLC2272IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		22721	Samples
TLC2272IP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC2272IP	Samples
TLC2272IPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC2272IP	Samples
TLC2272IPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		Y2272	Samples
TLC2272IPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		Y2272	Samples
TLC2272IPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI			
TLC2272IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		Y2272	Samples
TLC2272IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		Y2272	Samples





Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
TLC2272MD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2272M	Sample
TLC2272MDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272M	Sample
TLC2272MDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2272M	Sample
TLC2272MDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2272M	Sample
TLC2272MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9555201Q2A TLC2272 MFKB	Sample
TLC2272MJG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	TLC2272MJG	Sample
TLC2272MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9555201QPA TLC2272M	Sample
TLC2272MP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI	-55 to 125		
TLC2272MUB	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type	-55 to 125	9555201QHA TLC2272M	Sample
TLC2272QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		C2272Q	Sample
TLC2272QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C2272Q	Sample
TLC2272QPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		T2272Q	Sample
TLC2274ACD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2274AC	Sample
TLC2274ACDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2274AC	Sample
TLC2274ACDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2274AC	Sample
TLC2274ACDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	2274AC	Sampl
TLC2274ACN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TLC2274ACN	Sample
TLC2274ACNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TLC2274ACN	Sample





Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samp
TLC2274ACPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P2274A	Samp
TLC2274ACPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P2274A	Samp
TLC2274ACPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P2274A	Sam
TLC2274ACPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P2274A	Sam
TLC2274AID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2274AI	Sam
TLC2274AIDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2274AI	Sam
TLC2274AIDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2274AI	Sam
TLC2274AIDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2274AI	Sam
TLC2274AIN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TLC2274AIN	Sam
TLC2274AINE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	TLC2274AIN	Sam
TLC2274AIPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	Y2274A	San
TLC2274AIPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	Y2274A	San
TLC2274AIPWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 125		
TLC2274AIPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	Y2274A	San
TLC2274AIPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	Y2274A	San
TLC2274AMD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	2274AM	San
TLC2274AMDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2274AM	San
TLC2274AMDR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-55 to 125		
TLC2274AMDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		2274AM	Sam



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Orderable Device		Package Type	_	Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TLC2274AMFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9318202Q2A TLC2274 AMFKB	Sample
TLC2274AMJB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9318202QC A TLC2274AMJB	Sample
TLC2274AMWB	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9318202QD A TLC2274AMWB	Sample
TLC2274AQD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLC2274A	Sampl
TLC2274AQDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PJ2274A	Sampl
TLC2274AQDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLC2274A	Sampl
TLC2274AQDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PJ2274A	Samp
TLC2274CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC2274C	Samp
TLC2274CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC2274C	Samp
TLC2274CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC2274C	Sampl
TLC2274CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC2274C	Sampl
TLC2274CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC2274CN	Samp
TLC2274CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC2274CN	Samp
TLC2274CNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC2274	Samp
TLC2274CPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		P2274	Samp
TLC2274CPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		P2274	Samp
TLC2274CPWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI			





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
TLC2274CPWR	ACTIVE	TSSOP	PW	14	2000	(2) Green (RoHS & no Sb/Br)	(6) CU NIPDAU	(3) Level-1-260C-UNLIM		(4/5) P2274	Samples
TLC2274CPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P2274	Sample
TLC2274ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC2274I	Sample
TLC2274IDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC2274I	Sample
TLC2274IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC2274I	Sample
TLC2274IDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC2274I	Sample
TLC2274IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		TLC2274IN	Sample
TLC2274IPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		Y2274	Sample
TLC2274IPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		Y2274	Sample
TLC2274IPWLE	OBSOLETI	TSSOP	PW	14		TBD	Call TI	Call TI			
TLC2274IPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		Y2274	Sample
TLC2274IPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		Y2274	Sample
TLC2274MD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	TLC2274M	Sample
TLC2274MDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PJ2274M	Sample
TLC2274MDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	TLC2274M	Sample
TLC2274MDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PJ2274M	Sample
TLC2274MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9318201M2A TLC2274 MFKB	Sample
TLC2274MJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	TLC2274MJ	Sample



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Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TLC2274MJB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9318201MC A TLC2274MJB	Samples
TLC2274MN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	TLC2274MN	Samples
TLC2274MWB	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9318201QD A TLC2274MWB	Samples
TLC2274QD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLC2274	Samples
TLC2274QDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC2274	Samples
TLC2274QDR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 125	TLC2274	
TLC2274QDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		TLC2274	Samples
TLC2274Y	PREVIEW	DIESALE	Υ	0		TBD	Call TI	Call TI			

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



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(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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OTHER QUALIFIED VERSIONS OF TLC2272, TLC2272A, TLC2272AM, TLC2272M, TLC2274A, TLC2274AM, TLC2274AM, TLC2274AM:

- Catalog: TLC2272A, TLC2272, TLC2274A, TLC2274
- Automotive: TLC2272-Q1, TLC2272A-Q1, TLC2272A-Q1, TLC2272-Q1, TLC2274-Q1, TLC2274A-Q1, TLC2274A-Q1, TLC2274A-Q1
- Enhanced Product: TLC2272A-EP, TLC2272A-EP, TLC2274-EP, TLC2274A-EP, TLC2274A-EP, TLC2274A-EP
- Military: TLC2272M, TLC2272AM, TLC2274AM

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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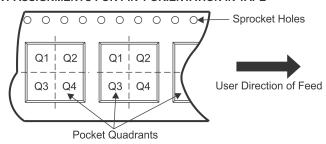
TAPE AND REEL INFORMATION



TAPE DIMENSIONS KO P1 BO W Cavity AO

	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



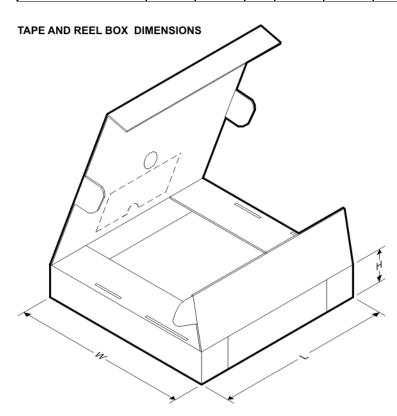
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
5962-9555201NXDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC2272ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC2272ACPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC2272AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC2272AMDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC2272AMDRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC2272AQDR	SOIC	D	8	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
TLC2272CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC2272CPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC2272IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC2272IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC2272MDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC2272QDR	SOIC	D	8	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
TLC2272QPWRG4	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC2274ACDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC2274ACPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLC2274AIDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC2274AIPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC2274AQDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC2274CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC2274CNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TLC2274CPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLC2274IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC2274IPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLC2274MDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC2274MDRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLC2274QDRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
5962-9555201NXDR	SOIC	D	8	2500	367.0	367.0	38.0
TLC2272ACDR	SOIC	D	8	2500	340.5	338.1	20.6
TLC2272ACPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
TLC2272AIDR	SOIC	D	8	2500	340.5	338.1	20.6
TLC2272AMDR	SOIC	D	8	2500	367.0	367.0	38.0
TLC2272AMDRG4	SOIC	D	8	2500	367.0	367.0	38.0
TLC2272AQDR	SOIC	D	8	2500	340.5	338.1	20.6
TLC2272CDR	SOIC	D	8	2500	340.5	338.1	20.6



PACKAGE MATERIALS INFORMATION

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC2272CPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
TLC2272IDR	SOIC	D	8	2500	340.5	338.1	20.6
TLC2272IPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
TLC2272MDR	SOIC	D	8	2500	367.0	367.0	38.0
TLC2272QDR	SOIC	D	8	2500	340.5	338.1	20.6
TLC2272QPWRG4	TSSOP	PW	8	2000	367.0	367.0	35.0
TLC2274ACDR	SOIC	D	14	2500	333.2	345.9	28.6
TLC2274ACPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
TLC2274AIDR	SOIC	D	14	2500	333.2	345.9	28.6
TLC2274AIPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
TLC2274AQDR	SOIC	D	14	2500	367.0	367.0	38.0
TLC2274CDR	SOIC	D	14	2500	333.2	345.9	28.6
TLC2274CNSR	SO	NS	14	2000	367.0	367.0	38.0
TLC2274CPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
TLC2274IDR	SOIC	D	14	2500	333.2	345.9	28.6
TLC2274IPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
TLC2274MDR	SOIC	D	14	2500	367.0	367.0	38.0
TLC2274MDRG4	SOIC	D	14	2500	367.0	367.0	38.0
TLC2274QDRG4	SOIC	D	14	2500	367.0	367.0	38.0

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



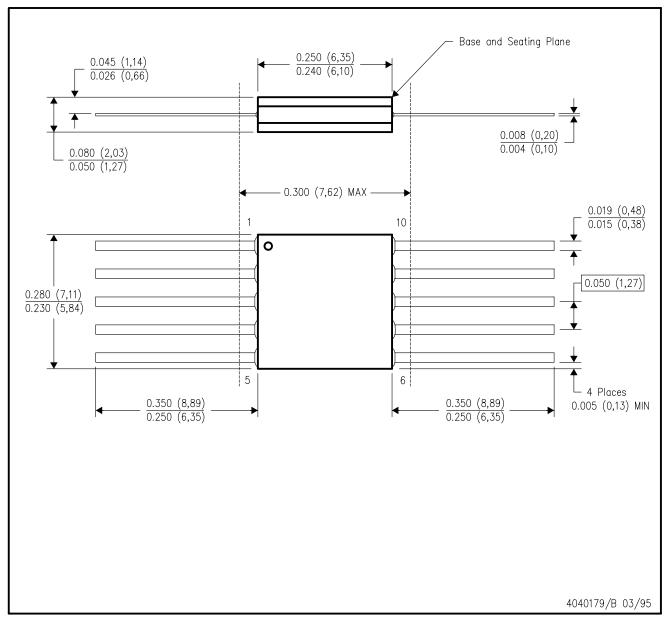
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

U (S-GDFP-F10)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PS (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153, variation AA.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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